Supplier Name: Texas Contact Info: ti.com Form/Declaration Type: Distrib Created on: 05/20,7

Texas Instruments Inc. (DUNS# 00-732-1904) ti.com/support

Distribute - RoHS and IEC 62474 DB 05/20/2022

Details for "REF3120AIDBZR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
REF3120AIDBZR	NIPDAUAG	Level-1-260C-UNLIM	Ext-Mfg	DBZ 3	2.9x1.3x0.95	11.2

*Total Device Mass

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The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

	Homogeneous Material Level			Component Level			
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.012423	97.665094	976651	0.11056	1106
Precious Metals	Palladium	7440-05-3	0.000297	2.334906	23349	0.002643	26
Sub-Total			0.01272	100	1000000	0.113203	1132
Die Attach Adhesive							
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.026223	29.999657	299997	0.233375	2334
Other Inorganic Materials	Silica	7631-86-9	0.003934	4.500578	45006	0.035011	350
Thermoplastics	Epoxy	85954-11-6	0.057254	65.499765	654998	0.50954	5095
Sub-Total			0.087411	100	1000000	0.777927	7779
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	4.724385	97.41	974100	42.045335	420453
Copper and Its Alloys	Iron	7439-89-6	0.11543	2.38	23800	1.027286	10273
Copper and Its Alloys	Phosphorus	7723-14-0	0.00388	0.08	800	0.034531	345
Zinc and Its Alloys	Zinc	7440-66-6	0.006305	0.13	1300	0.056112	561
Sub-Total			4.85	100	1000000	43.163264	431633
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.14595	97.3	973000	1.298903	12989
Precious Metals	Gold	7440-57-5	0.00045	0.3	3000	0.004005	40
Precious Metals	Palladium	7440-05-3	0.00315	2.1	21000	0.028034	280
Precious Metals	Silver	7440-22-4	0.00045	0.3	3000	0.004005	40
Sub-Total			0.15	100	1000000	1.334946	13349
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	4.691481	86.999998	870000	41.752501	417525
Other Plastics and Rubber	Carbon Black	1333-86-4	0.005393	0.100009	1000	0.047996	480
Thermoplastics	Epoxy	85954-11-6	0.695633	12.899993	129000	6.190885	61909
Sub-Total			5.392507	100	1000000	47.991382	479914
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.743769	100	1000000	6.619278	66193
Sub-Total			0.743769	100	1000000	6.619278	66193
Total			11 236407			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

T certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

Th bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. The may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. The material content information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/20/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Po-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.